

# **Wencon Rapid**

The fast curing multi purpose epoxy compound for repair and rebuilding of deteriorated metal parts.

- Wide range of applications
- Fast curing reduced down time
- Strong adhesion to all metal surfaces
- Simple mixing and application
- Convenient unit sizes

#### **General information**

Wencon Rapid is a fast curing, two-component epoxy compound suitable for a wide range of applications within emergency repairs and maintenance.

Wencon Rapid shows many of the characteristics of metals, which together with outstanding adhesion to all metallic surfaces makes the repair compound highly suitable for repair of corroded and worn metals.

Wencon Rapid is non conducting and will therefore not cause bi-metallic corrosion. After curing the compound is resistant to oil, water, salt water and most diluted acids and a range of solvents. Heat resistance ranges from 60° C (140°F) in corrosive and heavy load environments and up to 250° C (482°F) when applied as a filling compound.

#### **Application areas**

Wencon Rapid is very suitable for applications where thicker layers of material are required, as the compound quickly sets and becomes solid. Typical applications are corroded tanks, pump housings and impellers, valves, tubes, pipes, heat exchangers, flange faces, seats, worn shafts, hydraulic rams and all emergency repairs, where a short curing time is required. The compound can also be used as a filling compound.

#### **Mixing**

Wencon products are designed to be simple to use and cost effective. Easy mixing ratio (1:1 by volume) reduces waste to a minimum and high specific volume gives high coverage rates.











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Product numbers:		IMPA no.	ISSA no.
No. 1000	Wencon Rapid, 1 kg (2,2 lb) unit	812347	75.553.21
No. 1005	Wencon Rapid 8, 8x125g (8x0,28 lb) unit	812343	75.553.22

## **WENCON®**

#### **GENERAL DESCRIPTION**

Fast curing two-component solvent free paste consistency epoxy repair compound.

## SURFACE PREPARATION

The surface must always be dry, clean and degreased

## Applying to new steel surface:

- Grit blasting to SA 2,5
- if Grit blasting is not possible use grinding
- after grinding the surface must be degreased with Wencon Bio Cleaner

#### Repairing old steel surface:

- Grit blasting to SA 2,5
- Sweat out water and salts
- Grit blasting to SA 2,5 again
- Profile 75 microns

## **MIXING RATIO**

Mix by volume 1:1. Mix until an even colour is obtained.

## POT LIFE

Depending on amount mixed and temperature. Mixed in small amounts, the pot life is approximately 10-20 minutes at 20°C (68°F)

## APPLYING

Wencon Rapid has a paste consistency and is applied by spatula, also on vertical surfaces.

#### **CURING TIME**

Curing will take place in 40-90 minutes at 20°C (68°F)

#### REDUCED CURING TIME WITH INFRARED

This product is tested with and suitable for infrared curing. Curing with infrared radiation can reduce curing time significantly. Result can vary, depending on circumstances and equipment used.

#### MACHINABLE

After curing, the product can be machined, drilled and worked like metal.

## TECHNICAL DATA

Hardness Shore D: 81 (DIN 53505)

Tensile strength: 9,2 N/mm<sup>2</sup> - 1310 p.s.i. (**DIN 53454**)

## **Compressive strength:**

Modulus of elasticity: 2891 N/mm<sup>2</sup> - 411,000 p.s.i. (**DIN 53454**)

Rcrack: 112 N/mm<sup>2</sup> - 16,000 p.s.i. **(DIN 53454)** 

Shear adhesion: 20 N/mm<sup>2</sup> - (ASTM D1002) Adhesion to steel: 2,0 N/mm<sup>2</sup>- (ISO 4624)

### SPECIFIC VOLUME

709 cm<sup>3</sup> per kilogramme (43,3 cu inch/kg)

## TEMPERATURE RESISTANCE

Corrosion: 60°C (140° F) Light load: 120°C (248°F) As filler: 250°C (482°F)

## CHEMICAL RESISTANCE

The compound is resistant to oil, water, salt water and most diluted acids and alkalis as well as a range of solvents.

## SHELF LIFE

At 20°C (68°F): 3 years

#### HANDLING PRECAUTIONS

Read the Wencon Instruction for Use and the Material Safety Data Sheet.